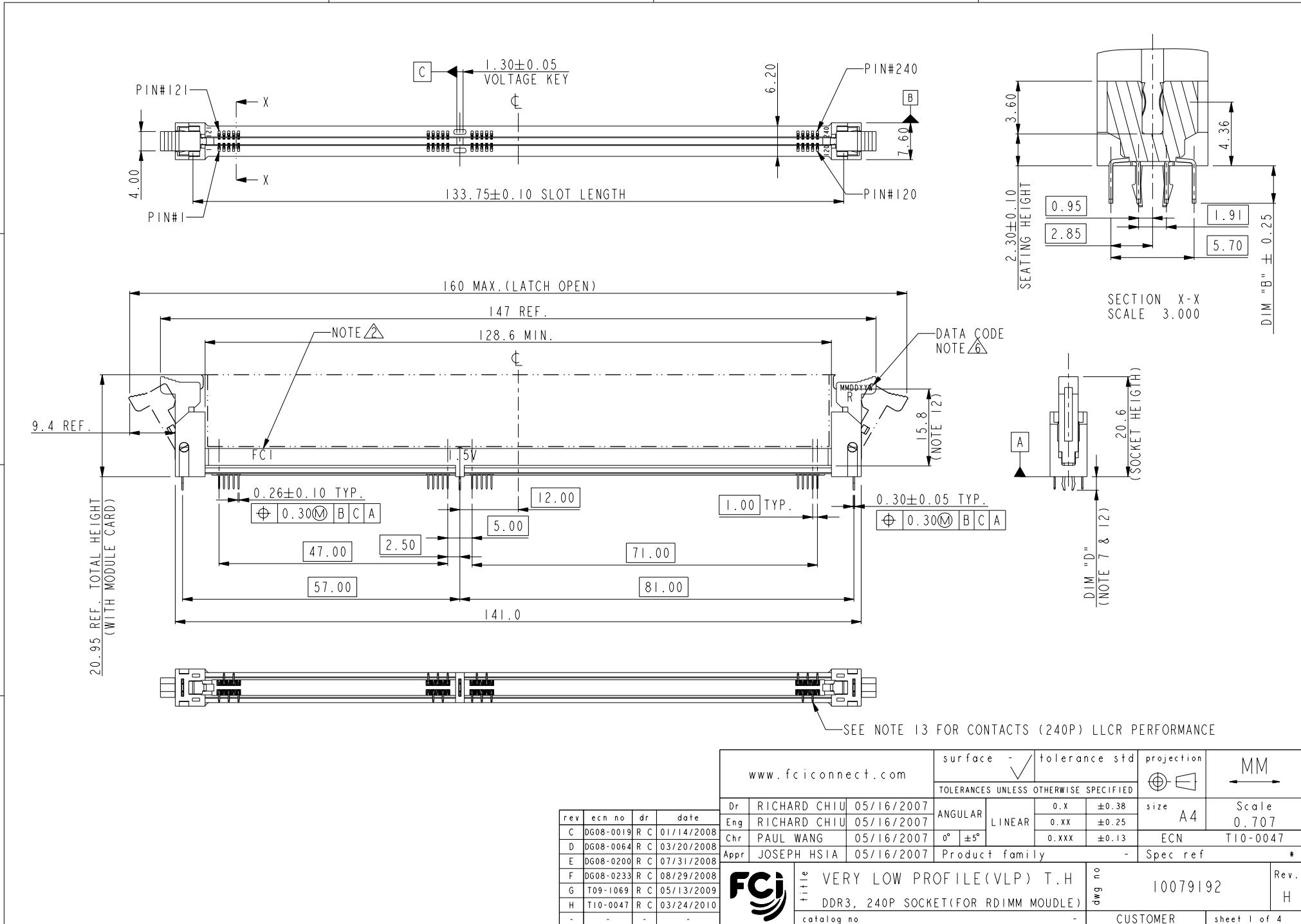


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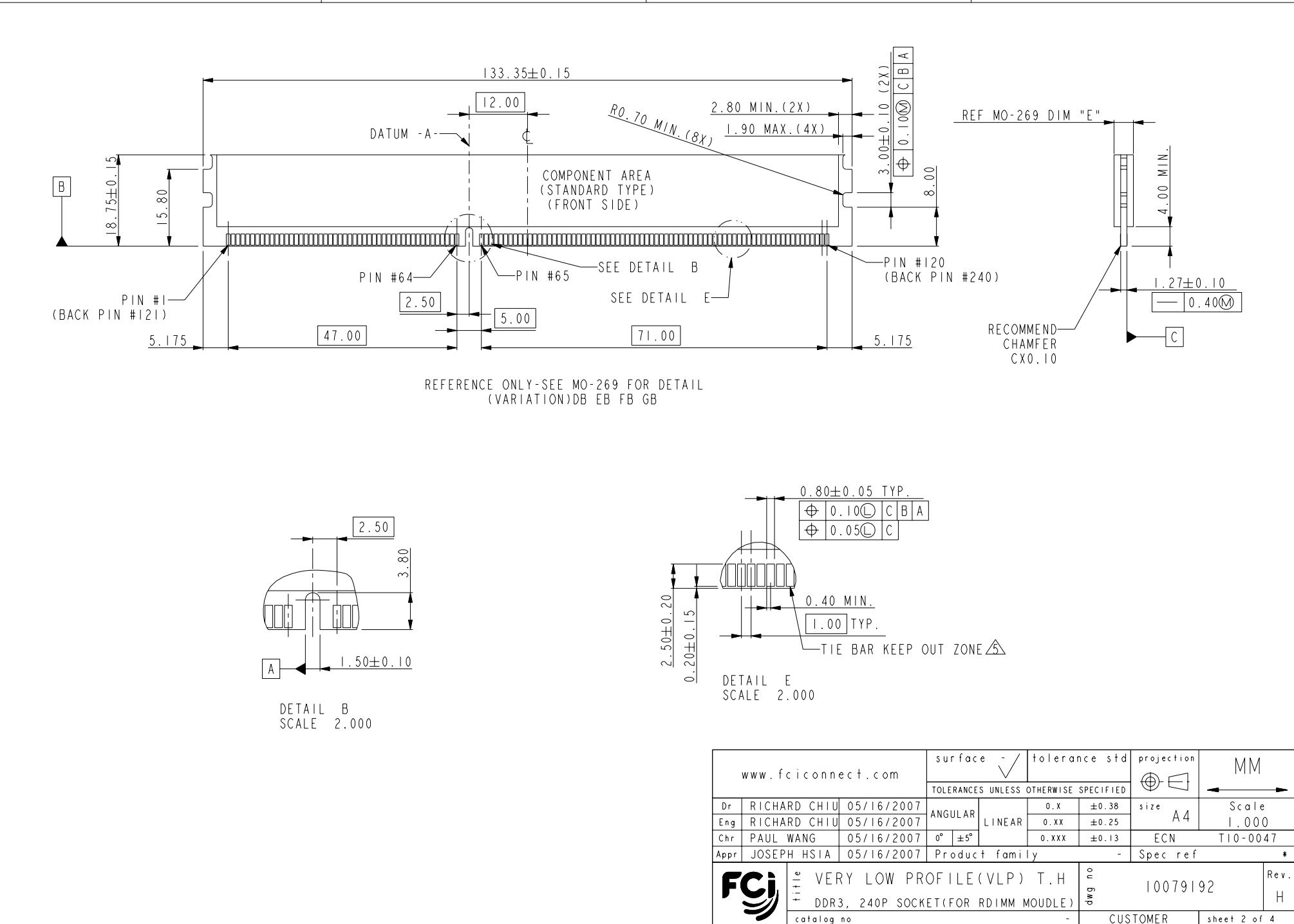


rev	ecn no	dr	date
C	DG08-0019	R C	01/14/2008
D	DG08-0064	R C	03/20/2008
E	DG08-0200	R C	07/31/2008
F	DG08-0233	R C	08/29/2008
G	T09-1069	R C	05/13/2009
H	T10-0047	R C	03/24/2010
-	-	-	-

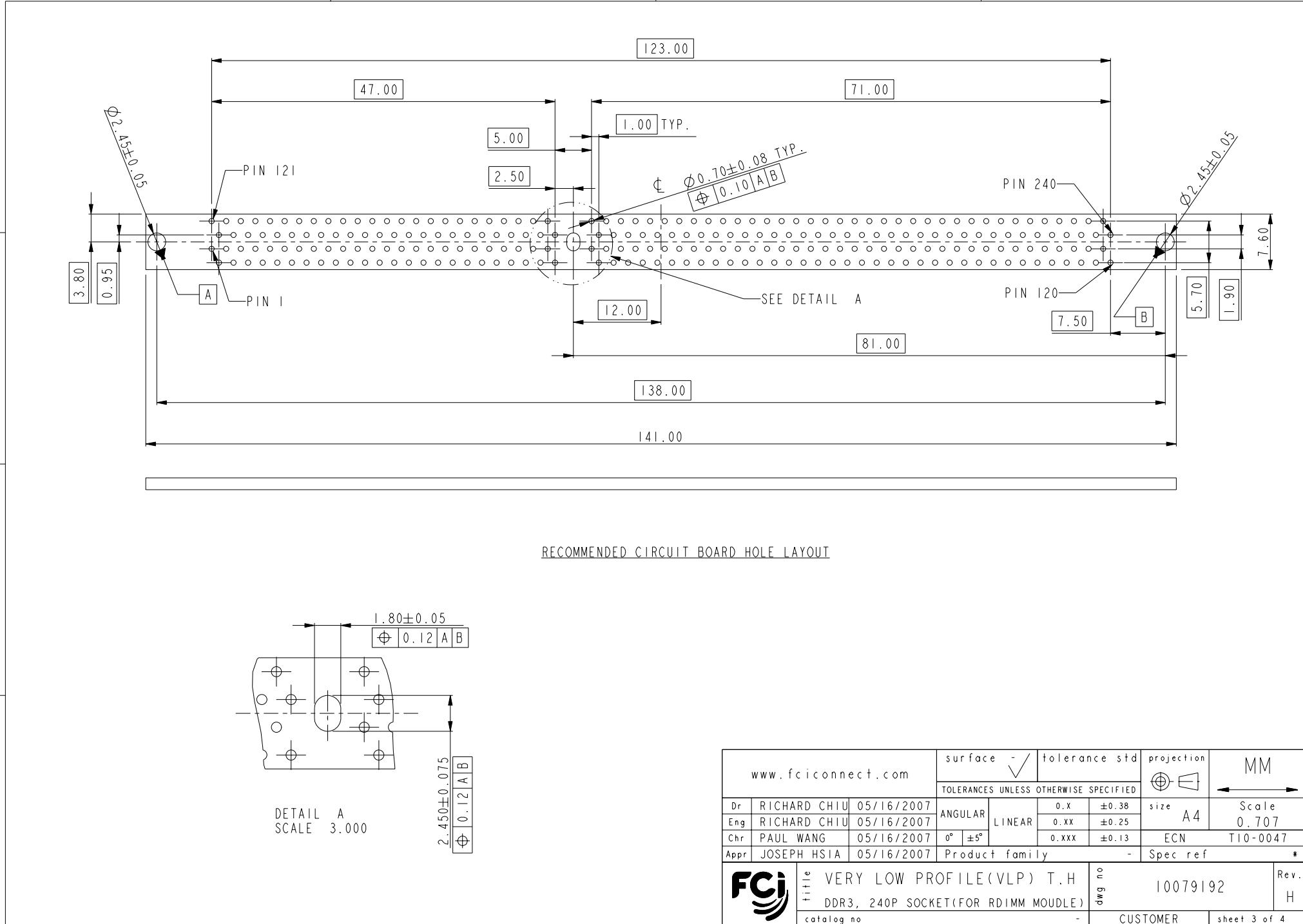
www.fciconnect.com				surface	tolerance std	projection	MM
Dr	RICHARD CHIU	05/16/2007					
Eng	RICHARD CHIU	05/16/2007	ANGULAR	0.X	±0.38	size	
Chr	PAUL WANG	05/16/2007	LINEAR	0.XX	±0.25	A4	Scale 0.707
Appr	JOSEPH HSIA	05/16/2007		0.XXX	±0.13	ECN	T10-0047
			Product family	-	Spec ref		*
FCI VERY LOW PROFILE (VLP) T.H DDR3, 240P SOCKET (FOR RDIMM MOUDLE)				dwg no	10079192	Rev.	
catalog no				-	CUSTOMER	sheet 1 of 4	

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www.fciconnect.com		surface	tolerance std	projection	MM
TOLERANCES UNLESS OTHERWISE SPECIFIED					
Dr	RICHARD CHIU	05/16/2007	ANGULAR	0.X	± 0.38
Eng	RICHARD CHIU	05/16/2007	LINEAR	0.XX	± 0.25
Chr	PAUL WANG	05/16/2007		0.XXX	± 0.13
Appr	JOSEPH HSIA	05/16/2007	Product family	-	Spec ref
FCI		VERY LOW PROFILE(VLP) T.H DDR3, 240P SOCKET(FOR RDIMM MOUDLE)		dwg no	Rev. H 10079192
catalog no		-		CUSTOMER	sheet 2 of 4



A

10079192 -

STYLE : MECHANICAL KEYING

I : 1.5 VOLT. W/ CENTER KEY

PLATING

CODE	CONTACT	SOLDERTAIL	UNDERPLATE
2LF	15 μ " (0.38um) MIN. GOLD		
3LF	30 μ " (0.76um) MIN. GOLD	100 μ " (2.54um) MIN. 100% MATTE TIN	50 μ " (1.27um) MIN. NICKEL OVERALL
4LF	3 μ " (0.076um) MIN. GOLD		

B

CONTACT & FORKLOCK LENGTH

CODE	DIM "B"	DIM "D"	PCB THICKNESS
00	2.67 mm	3.50 mm	1.60 mm (0.063")
11	3.18 mm	4.00 mm	2.36 mm (0.093")

COLOR OF HOUSING AND EJECTOR

0 : BLACK HOUSING + IVORY EJECTOR
 1 : BLACK HOUSING + AMBER EJECTOR (NOTE. 11)
 2 : BLACK HOUSING + BLACK EJECTOR
 8 : IVORY HOUSING + IVORY EJECTOR
 9 : IVORY HOUSING + BLACK EJECTOR



C

NOTES:

1. MATERIAL:
 HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
 EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
 TERMINAL: HIGH PERFORMANCE COPPER ALLOY
 METAL CLIP: COPPER ALLOY.

⚠ FCI LOGO TO BE APPROXIMATELY LOCATED AS SHOWN ON PRINT.

3. PRODUCT SPECIFICATION: GS-12-486.

4. PACKAGING SPECIFICATION: GS-14-899.

⚠ FOR OPTIMUM PERFORMANCE, THE TIE BAR IS TO BE ON AN INTERNAL LAYER SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.

⚠ THE DATE CODE IS SHOWN "MM-DD-YY-W". "W" MEANS PRODUCTION LINE. "R" MEANS FOR 'RDIMM' SOCKET.

7. THE REQUIRED PCB THICKNESS IS 1.60MM MINIMUM FOR BOARD LOCK RETENTION.

8. THIS SOCKET MEETS APPLICABLE JEDEC STD.; SOCKET OUTLINE SO-XXX, GAUGE GS-00X AND GS-00X. (SUSPENDED BY JEDEC)

9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

10. THE HOUSING WILL WITH STAND EXPOSURE TO $260 \pm 5^\circ\text{C}$ PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDERING APPLICATION.

11. AMBER EJECTOR OPTION IS ONLY FOR SOLDERING ENVIRONMENT TEMP. UNDER 170°C .

12. FROM SEATING PLANE TO TOP MODULE CARD ENGAGEMENT.

13. THIS SOCKET CONTACT EOL RESISTANCE IS DESIGNED TO BE 20 mohm MAX.

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A

B

C

D

D

www.fciconnect.com			surface	tolerance std	projection	MM
			TOLERANCES UNLESS OTHERWISE SPECIFIED			
Dr	RICHARD CHIU	05/16/2007	ANGULAR	0.X	± 0.38	size A4
Eng	RICHARD CHIU	05/16/2007	LINEAR	0.XX	± 0.25	Scale 1.000
Chr	PAUL WANG	05/16/2007		0.XXX	± 0.13	ECN T10-0047
Appr	JOSEPH HSIA	05/16/2007	Product family	-	Spec ref	*
 VERY LOW PROFILE (VLP) T.H DDR3, 240P SOCKET (FOR RDIMM MOUDLE)			dwg no	10079192	Rev. H	
catalog no			-	CUSTOMER	sheet 4 of 4	

Mouser Electronics

Authorized Distributor

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[10079192-10102LF](#)